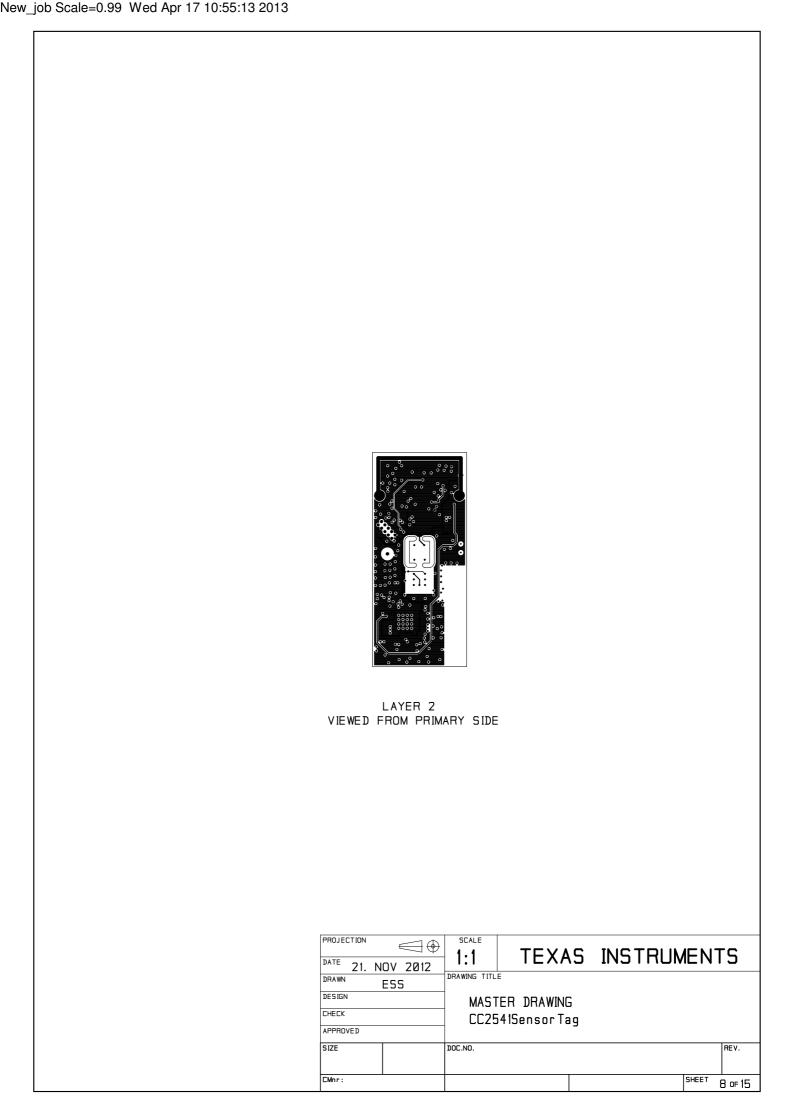
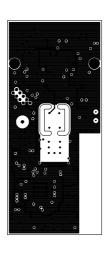


PRIMARY SIDE (LAYER 1) VIEWED FROM PRIMARY SIDE

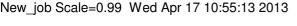
PROJECTION  DATE 24	•	SCALE 1:1	TEXA	S	INSTRUMENTS		
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LAYER 3 VIEWED FROM PRIMARY SIDE

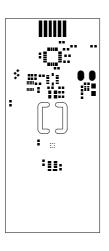
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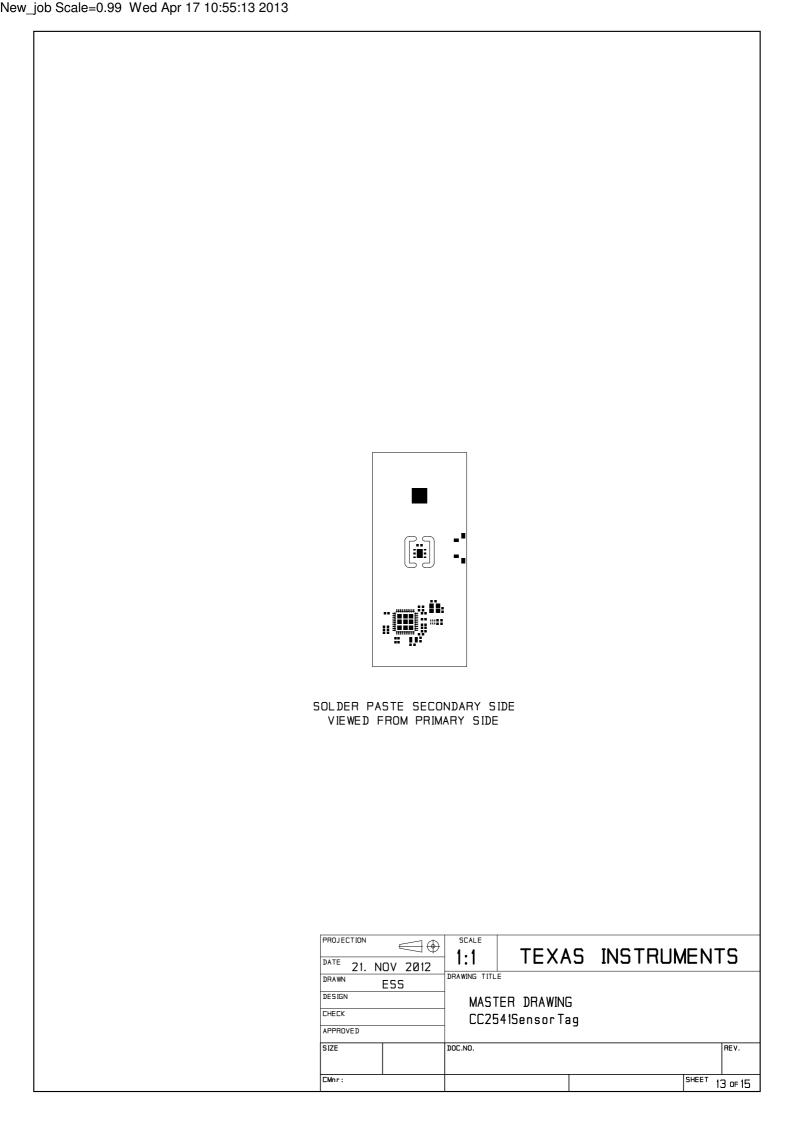
SECONDARY SIDE (LAYER 4) VIEWED FROM PRIMARY SIDE

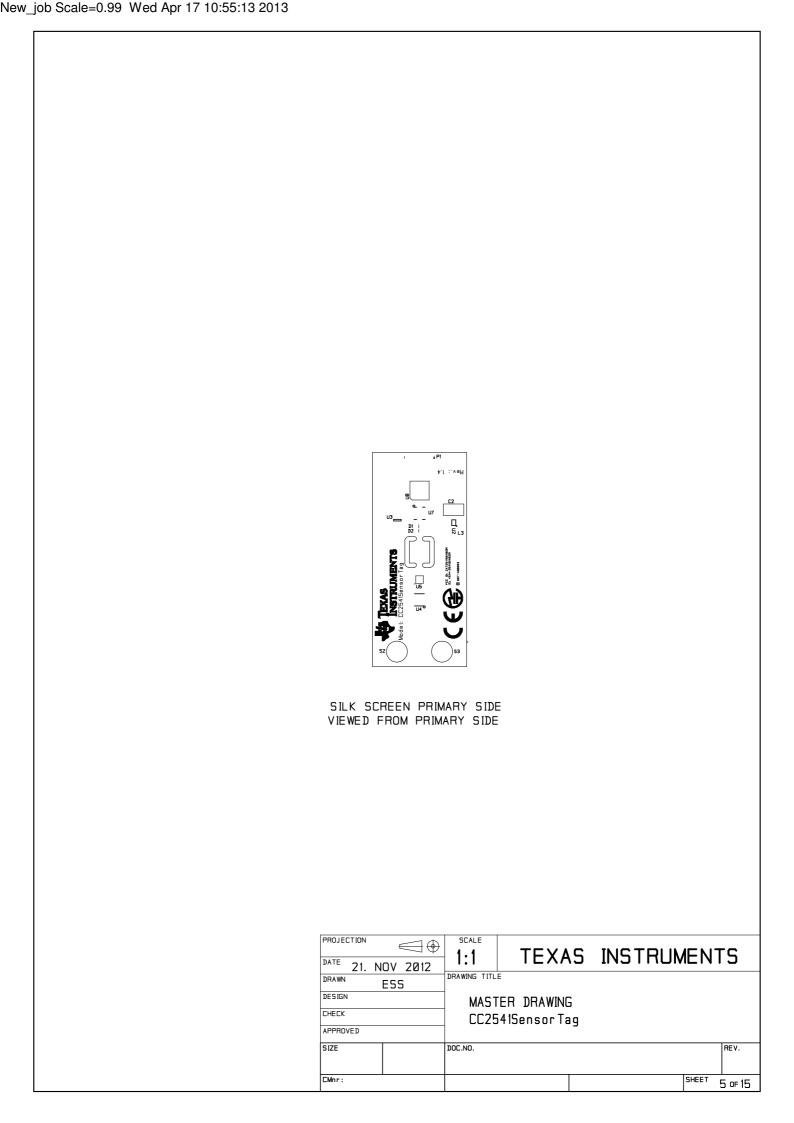
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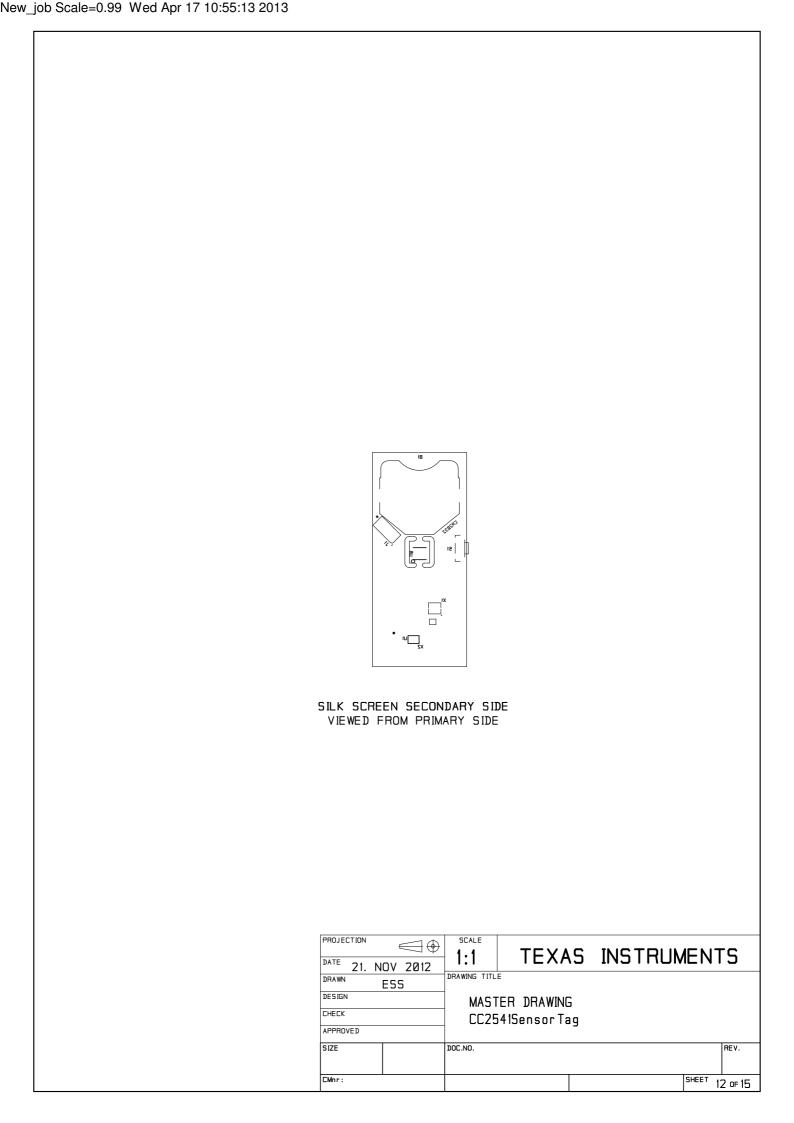


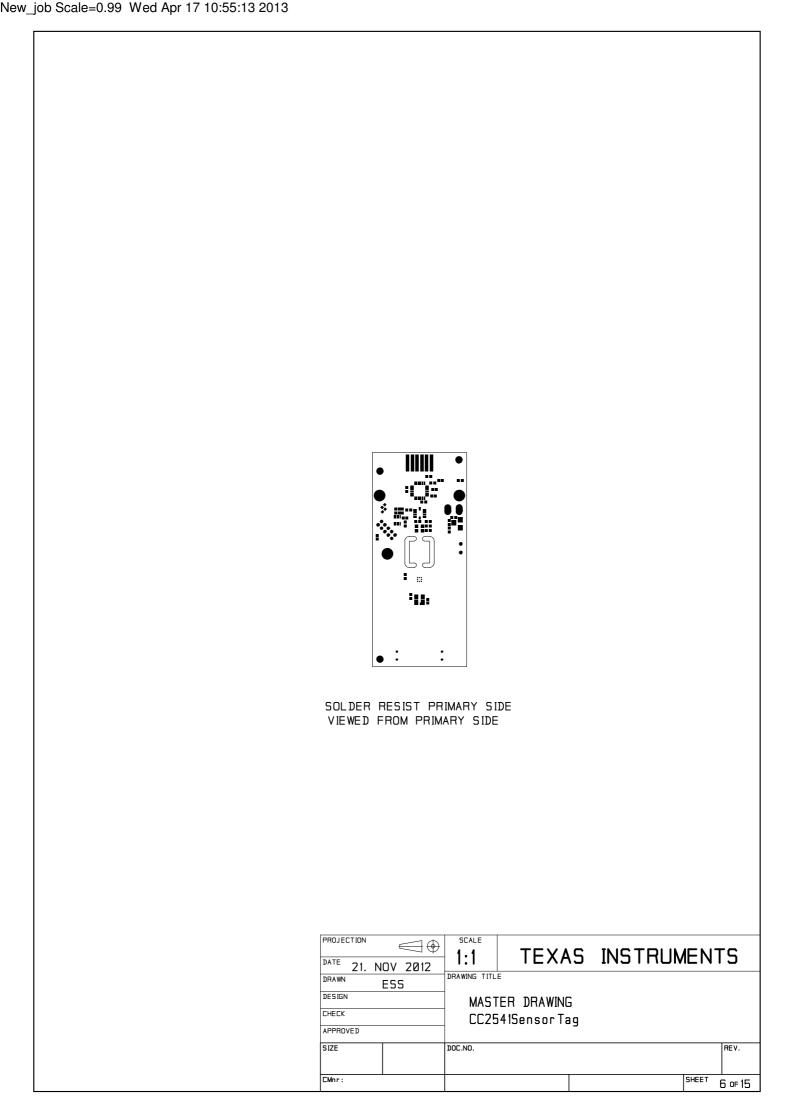
SOLDER PASTE PRIMARY SIDE VIEWED FROM PRIMARY SIDE

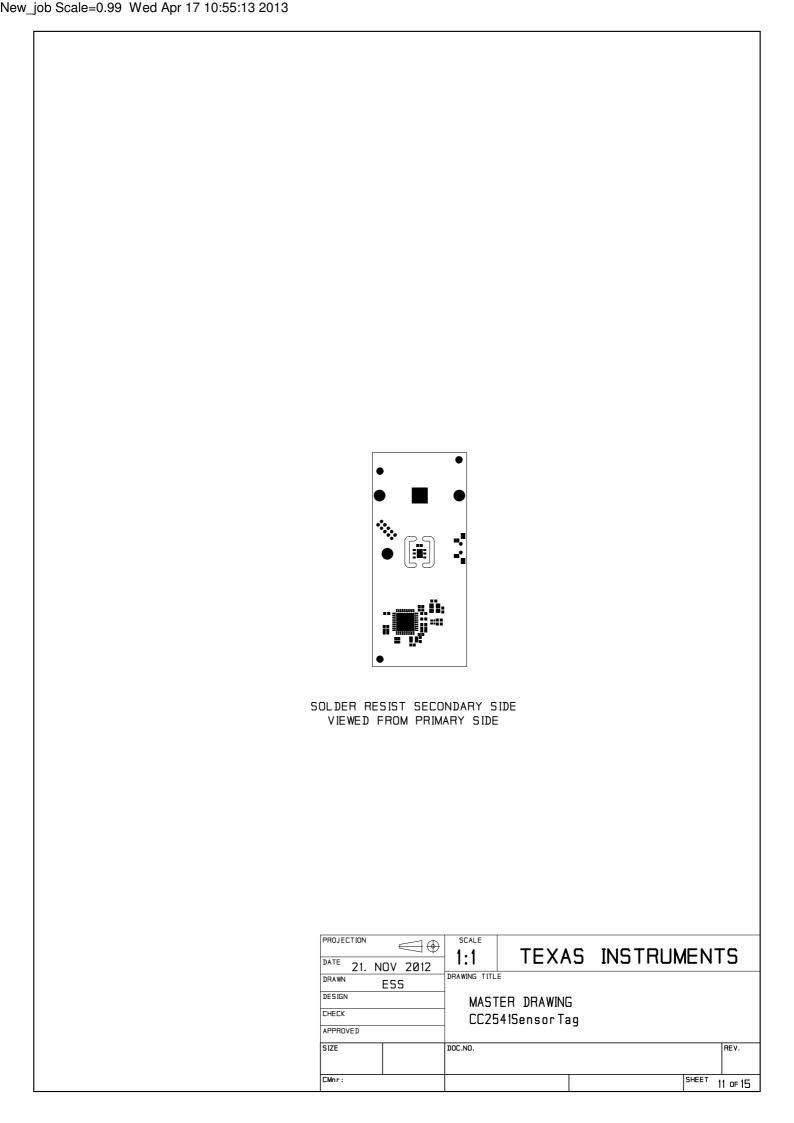
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